

FJAFS1510A

ESBC™ Rated NPN Power Transistor

Applications

- High-Voltage and High-Speed Power Switches
- Emitter-Switched Bipolar/MOSFET Cascodes (ESBC™)
- Smart Meters, Smart Breakers, SMPS, HV Industrial Power Supplies
- Motor Drivers and Ignition Drivers

ESBC Features (FDC655 MOSFET)

$V_{CS(ON)}$	I_C	Equiv. $R_{CS(ON)}$
0.426 V	6 A	$0.071 \Omega^{(1)}$

- Low Equivalent On Resistance
- Very Fast Switch: 150 kHz
- Avalanche Rated
- Low Driving Capacitance, No Miller Capacitance
- Low Switching Losses
- Reliable HV switch: No False Triggering due to High dv/dt Transients

Description

The FJAFS1510A is a low-cost, high-performance power switch designed to provide optimal performance when used in an ESBC™ configuration in applications such as: power supplies, motor drivers, smart grid, or ignition switches. The power switch is designed to operate up to 1550 volts and up to 6amps, while providing exceptionally low on-resistance and very low switching losses.

The ESBC™ switch is designed to be driven using off-the-shelf power supply controllers or drivers. The ESBC™ MOSFET is a low-voltage, low-cost, surface-mount device that combines low-input capacitance and fast switching. The ESBC™ configuration further minimizes the required driving power because it does not have Miller capacitance.

The FJAFS1510A provides exceptional reliability and a large operating range due to its square Reverse-Bias-Safe-Operating-Area (RBSOA) and rugged design. The device is avalanche rated and has no parasitic transistors so is not prone to static dv/dt failures.

The power switch is manufactured using a dedicated high-voltage bipolar process and is packaged in a high-voltage TO-3PF package.

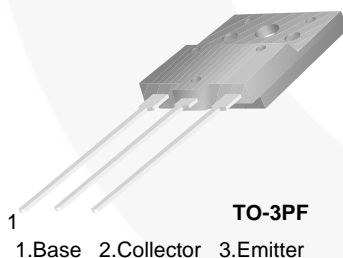


Figure 1. Pin Configuration

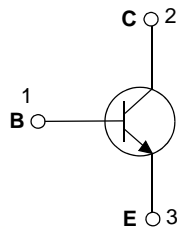


Figure 2. Internal Schematic Diagram

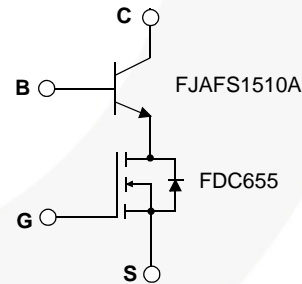


Figure 3. ESBC Configuration⁽²⁾

Ordering Information

Part Number	Marking	Package	Packing Method	Remarks
FJAFS1510ATU	J1510A	TO-3PF	TUBE	

Notes:

1. Figure of Merit.
2. Other Fairchild MOSFETs can be used in this ESBC application.

Absolute Maximum Ratings⁽³⁾

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-Base Voltage	1550	V
V_{CEO}	Collector-Emitter Voltage	750	V
V_{EBO}	Emitter-Base Voltage	6	V
I_C	Collector Current (DC)	6	A
P_C	Collector Dissipation ($T_C = 25^\circ\text{C}$)	60	W
T_J	Operating and Junction Temperature Range	-55 to +125	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$

Notes:

3. Pulse Test: Pulse Width = 5 ms, Duty Cycle 10%.

Thermal Characteristics

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.08	$^\circ\text{C}/\text{W}$

Electrical Characteristics

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{CES}	Collector Cut-off Current	$V_{CB} = 1400\text{ V}, R_{BE} = 0$			100	μA
I_{CBO}	Collector Cut-off Current	$V_{CB} = 800\text{ V}, I_E = 0$			10	μA
I_{EBO}	Emitter Cut-off Current	$V_{EB} = 4\text{ V}, I_C = 0$			100	μA
BV_{EBO}	Base-Emitter Breakdown Voltage	$I_E = 500\ \mu\text{A}, I_C = 0$	6			V
h_{FE1}	DC Current Gain	$V_{CE} = 5\text{ V}, I_C = 0.5\text{ A}$	15			
h_{FE2}	DC Current Gain	$V_{CE} = 5\text{ V}, I_C = 3\text{ A}$	7			
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 6\text{ A}, I_B = 1.5\text{ A}, T_A = 125^\circ\text{C}$		0.5		V
C_{ob}	Output Capacitance	$V_{CB} = 200\text{ V}, I_E = 0, f = 1\text{ MHz}$		27		pF

ESBC Configured Electrical Characteristics⁽⁴⁾Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
f_T	Current Gain Bandwidth Product	$I_C = 0.1\text{ A}, V_{CE} = 10\text{ V}$		15.4		MHz
t_{f_i}	Inductive Current Fall Time	$V_{GS} = 10\text{ V}, R_G = 47\ \Omega,$ $V_{Clamp} = 500\text{ V},$ $I_C = 1\text{ A}, I_B = 0.1\text{ A}, h_{FE} = 10,$ $L_C = 1\text{ mH},$ $SRF = 350\text{ kHz}$		115		ns
t_s	Inductive Storage Time			670		ns
V_{t_f}	Inductive Voltage Fall Time			160		ns
V_{t_r}	Inductive Voltage Rise Time			95		ns
t_c	Inductive Crossover Time			130		ns
t_{f_i}	Inductive Current Fall Time	$V_{GS} = 10\text{ V}, R_G = 47\ \Omega,$ $V_{Clamp} = 500\text{ V},$ $I_C = 5\text{ A}, I_B = 1\text{ A}, h_{FE} = 5,$ $L_C = 1\text{ mH},$ $SRF = 350\text{ kHz}$		12.5		ns
t_s	Inductive Storage Time			1100		ns
V_{t_f}	Inductive Voltage Fall Time			68		ns
V_{t_r}	Inductive Voltage Rise Time			110		ns
t_c	Inductive Crossover Time			150		ns
V_{CSW}	Maximum Collector Source Voltage at Turn-off without Snubber	$h_{FE} = 5, I_C = 6\text{ A}$	1550			V
$I_{GS(OS)}$	Gate-Source Leakage Current	$V_{GS} = \pm 20\text{ V}$		1.0		nA
$V_{CS(ON)}$	Collector-Source On Voltage	$V_{GS} = 10\text{ V}, I_C = 6\text{ A}, I_B = 2\text{ A}, h_{FE} = 3$		0.426		V
		$V_{GS} = 10\text{ V}, I_C = 4\text{ A}, I_B = 1.3\text{ A}, h_{FE} = 3$		0.213		V
		$V_{GS} = 10\text{ V}, I_C = 2\text{ A}, I_B = 0.67\text{ A}, h_{FE} = 3$		0.162		V
		$V_{GS} = 10\text{ V}, I_C = 1\text{ A}, I_B = 0.2\text{ A}, h_{FE} = 5$		0.141		V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{BS} = V_{GS}, I_B = 250\ \mu\text{A}$		1.9		V
C_{iss}	Input Capacitance ($V_{GS} = V_{CB} = 0$)	$V_{CS} = 25\text{ V}, f = 1\text{ MHz}$		470		pF
$Q_{GS(tot)}$	Gate-Source Charge $V_{CB} = 0$	$V_{GS} = 10\text{ V}, I_C = 6\text{ A}, V_{CS} = 25\text{ V}$		9		nC
$r_{DS(ON)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 6.3\text{ A}$		21		m Ω
		$V_{GS} = 10\text{ V}, I_D = 6.3\text{ A}, T_A = 125^\circ\text{C}$		30		m Ω
		$V_{GS} = 4.5\text{ V}, I_D = 5.5\text{ A}$		26		m Ω

Notes:

4. Used typical FDC655 MOSFET specifications in table. Table could vary if other Fairchild MOSFETs are used.

Typical Performance Characteristics

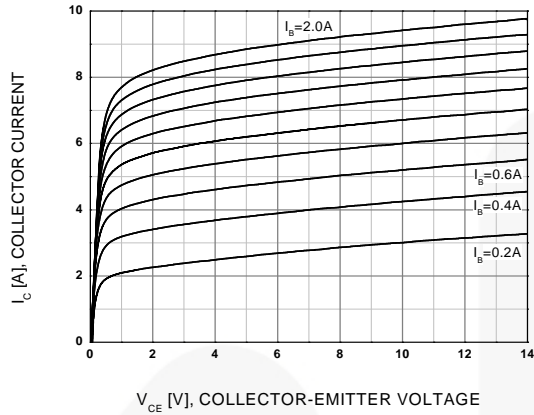


Figure 4. Static Characteristic

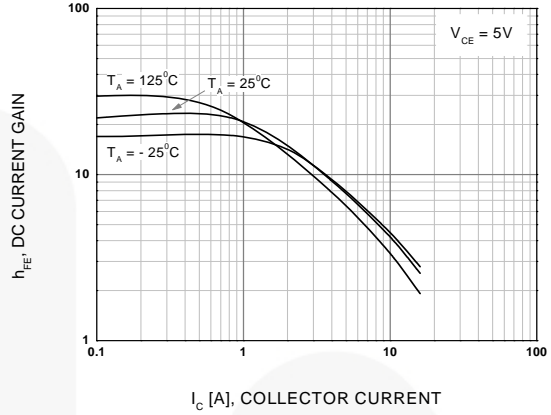
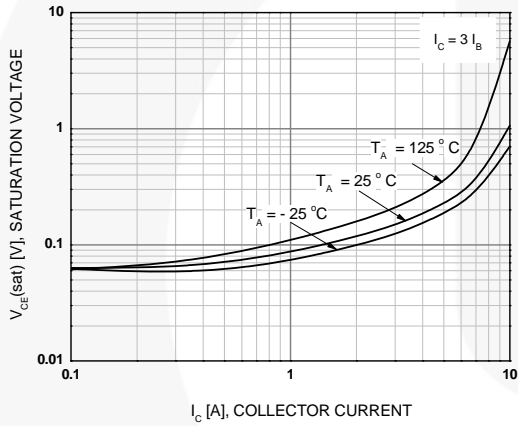
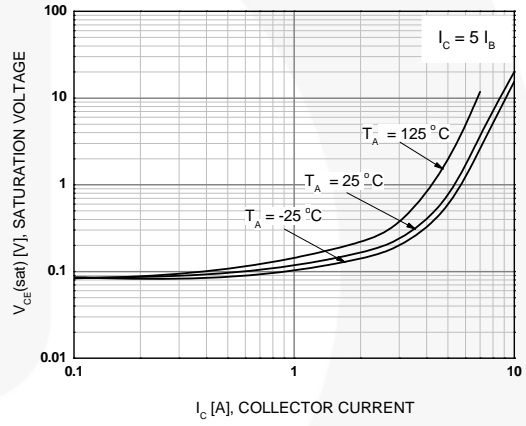


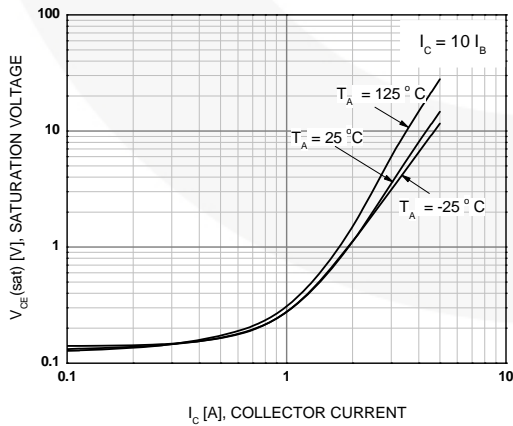
Figure 5. DC current Gain



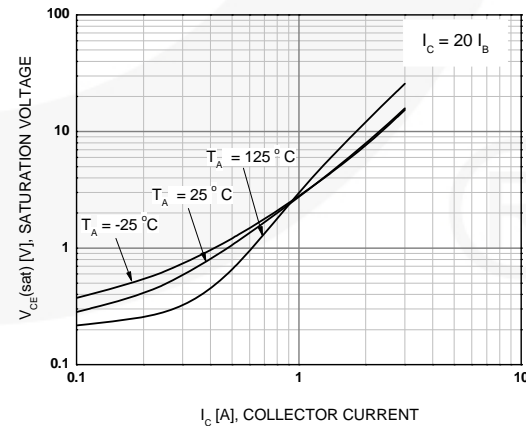
**Figure 6. Collector-Emitter Saturation Voltage
 $h_{FE}=3$**



**Figure 7. Collector-Emitter Saturation Voltage
 $h_{FE}=5$**



**Figure 8. Collector-Emitter Saturation Voltage
 $h_{FE}=10$**



**Figure 9. Collector-Emitter Saturation Voltage
 $h_{FE}=20$**

Typical Performance Characteristics (Continued)

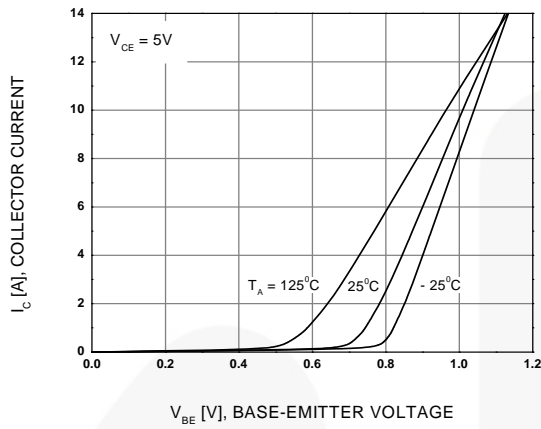


Figure 10. Base-Emitter On Voltage

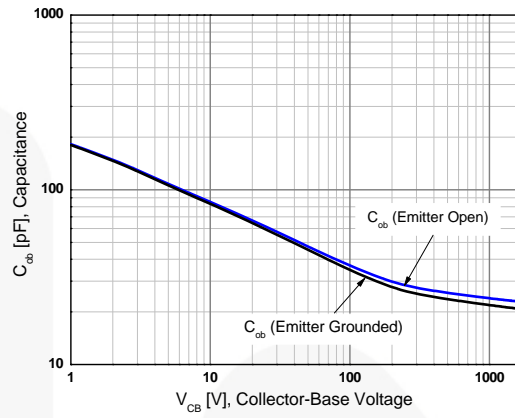


Figure 11. Capacitance

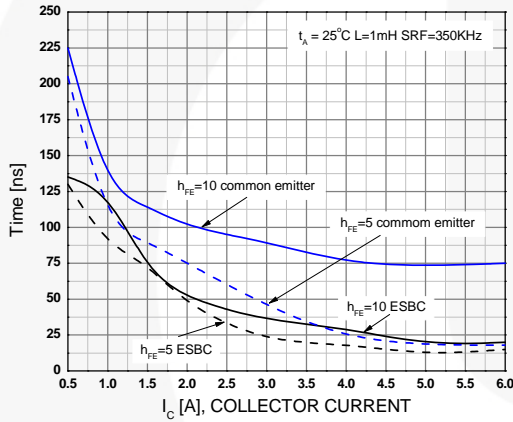


Figure 12. Inductive Load Collector Current Fall-time (t_r)

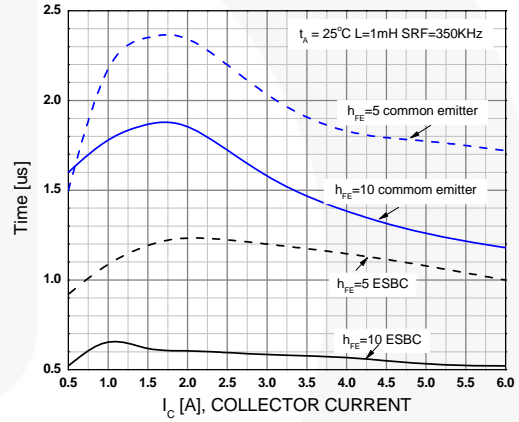


Figure 13. Inductive Load Collector Current Storage time (t_{stg})

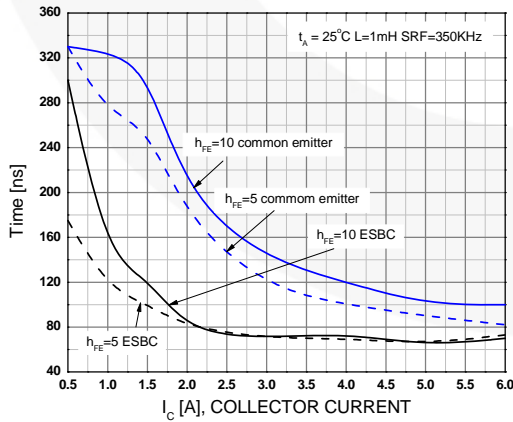


Figure 14. Inductive Load Collector Voltage Fall-time (t_r)

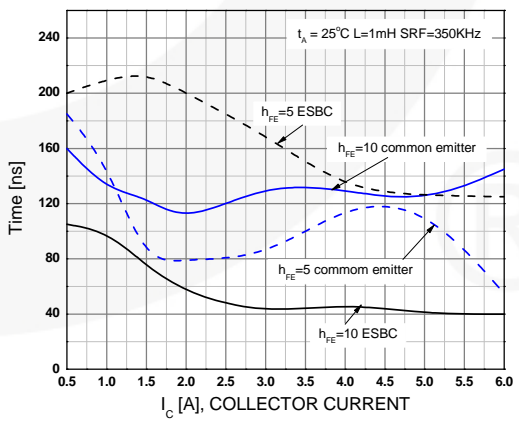


Figure 15. Inductive Load Collector Voltage Rise-time (t_r)

Typical Performance Characteristics (Continued)

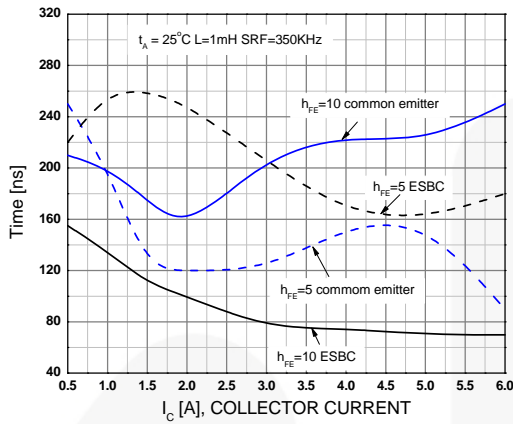


Figure 16. Inductive Load Collector Current/Voltage Crossover (t_c)

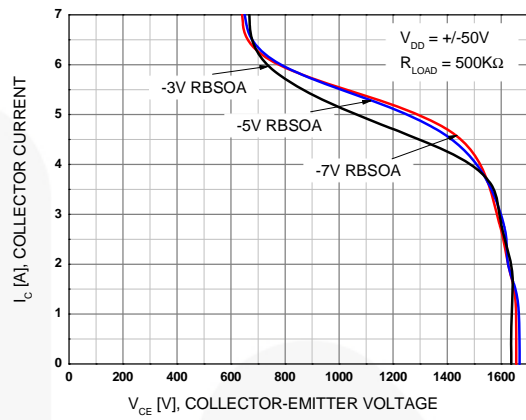


Figure 17. Reverse Bias Safe Operating Area

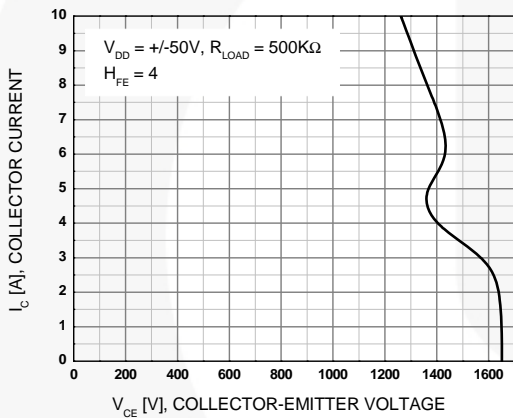


Figure 18. ESBC RBSOA

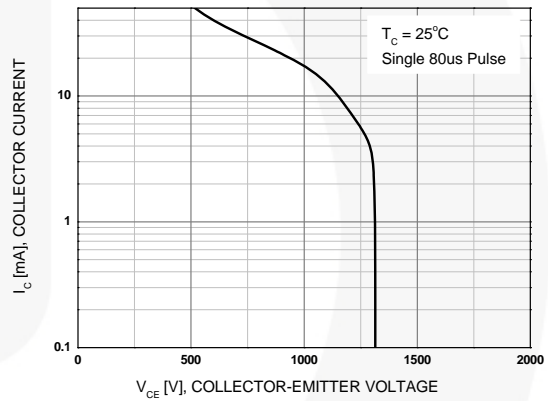


Figure 19. Forward Bias Safe Operating Area

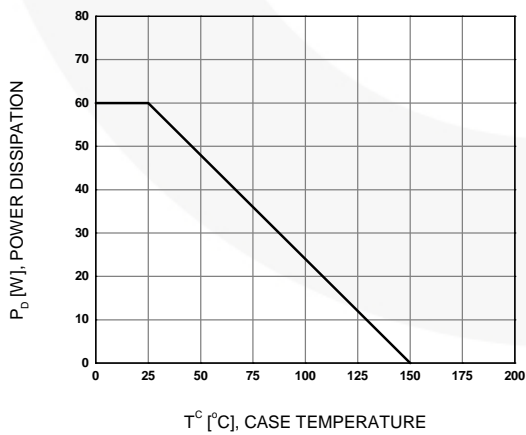


Figure 20. Power Derating

Test Circuits

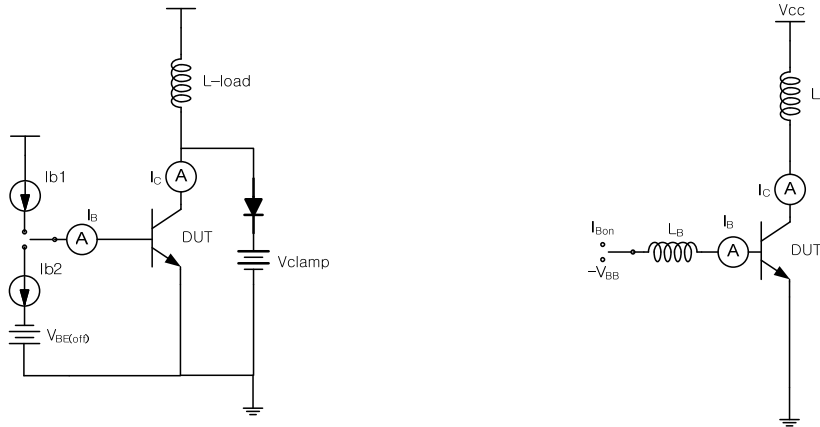


Figure 21. Test Circuit For Inductive Load and Reverse Bias Safe Operating

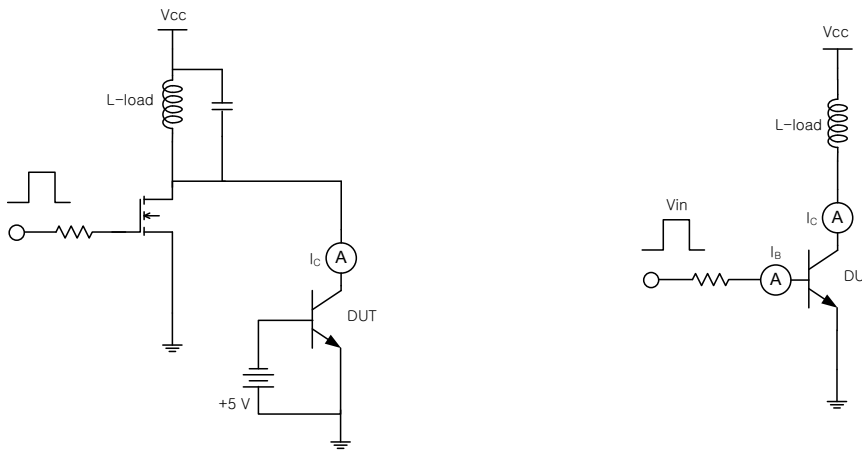


Figure 22. Energy Rating Test Circuit

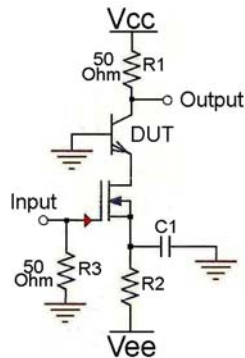


Figure 23. Ft Measurement

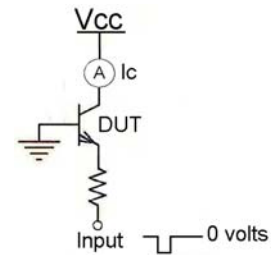


Figure 24. FBSOA

Test Circuits (Continued)

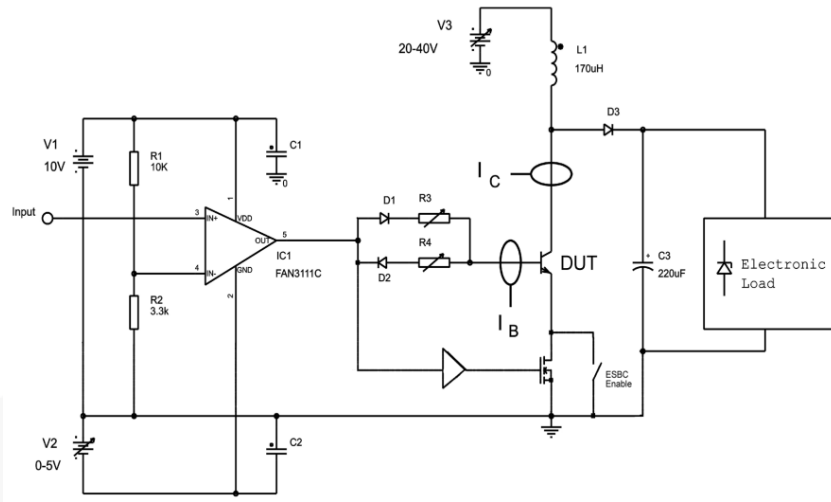


Figure 25. Simplified Saturated Switch Driver Circuit

Functional Test Waveforms

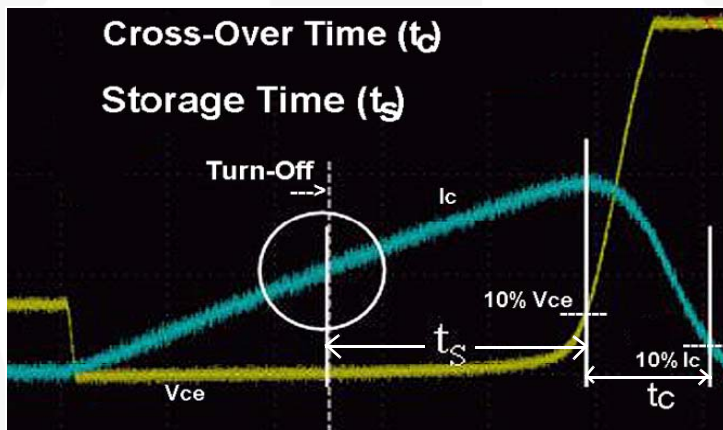


Figure 26. Crossover Time Measurement

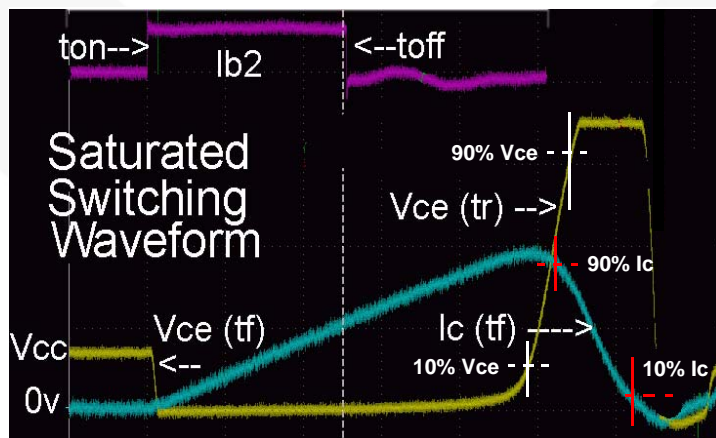


Figure 27. Saturated Switching Waveform

Functional Test Waveforms (Continued)

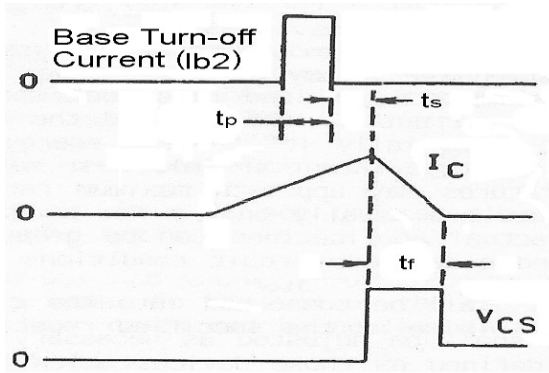


Figure 28. Storage Time - Common Emitter
Base turn off (I_{b2}) to I_C Fall-time

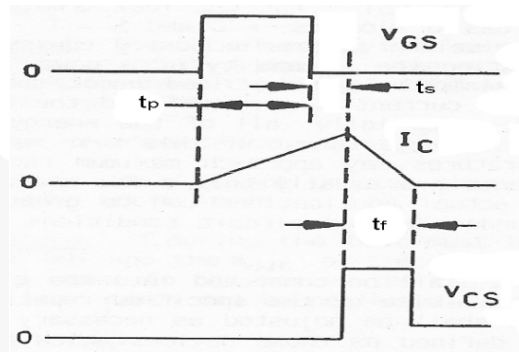
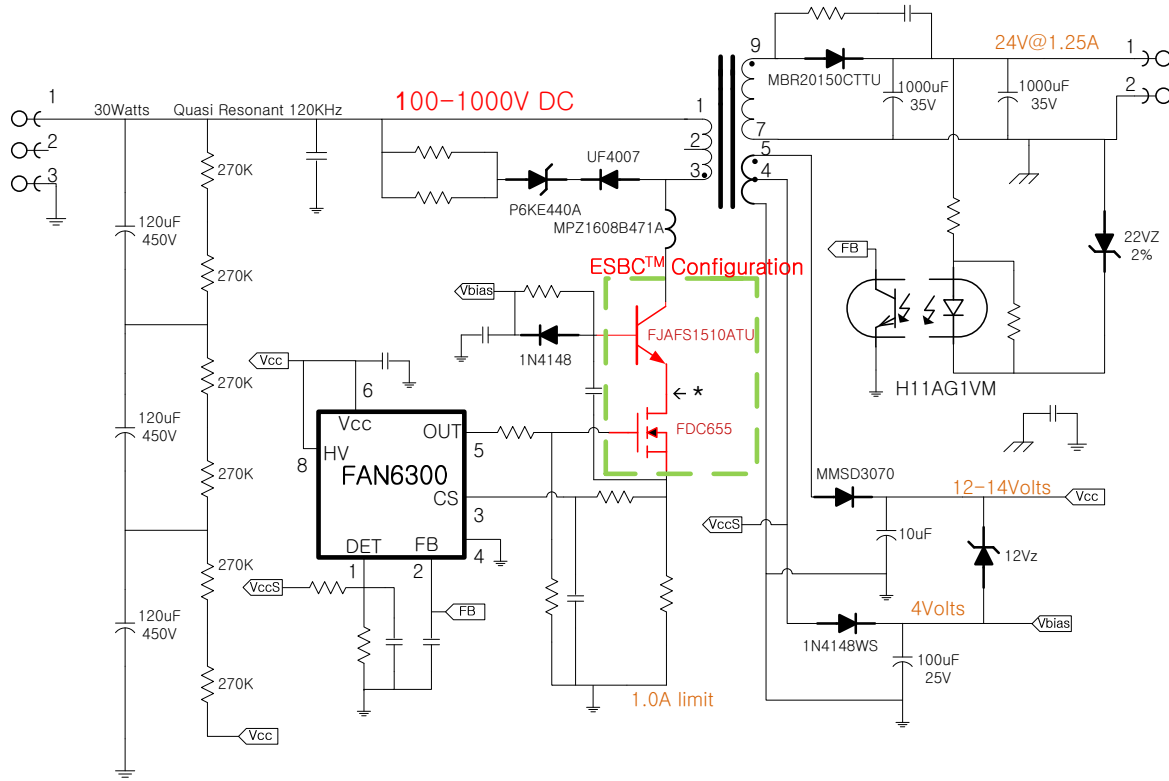


Figure 29. Storage Time - ESBC FET
Gate (off) to I_C Fall-time

Very Wide Input Voltage Range Supply

- 30 W; Secondary-Side Regulation: 3 Capacitor Input; Quasi Resonant



* Make short as possible

Figure 30. Very Wide Input Voltage Range Supply

Driving ESBC Switches

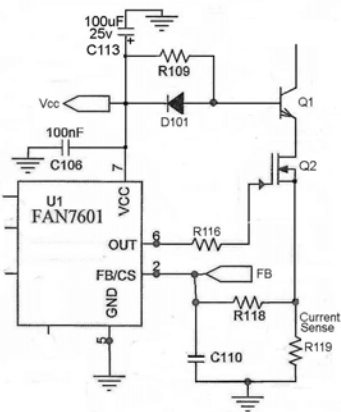


Figure 31. V_{CC} Derived

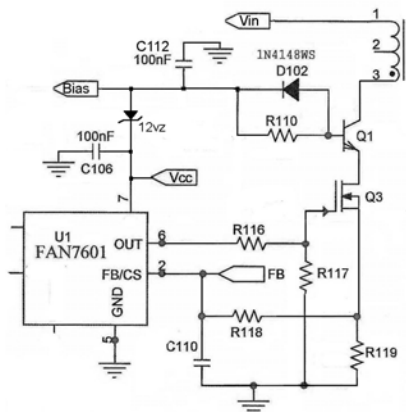


Figure 32. V_{BIAS} Supply Derived

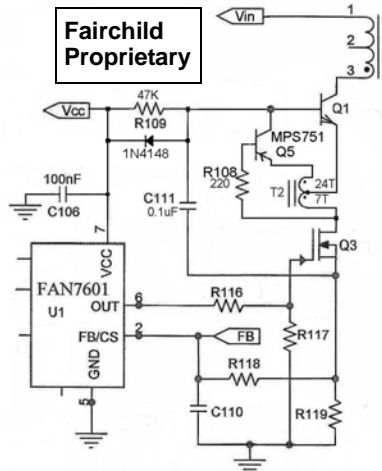


Figure 33. Proportional Drive

Physical Dimensions

TO-3PF

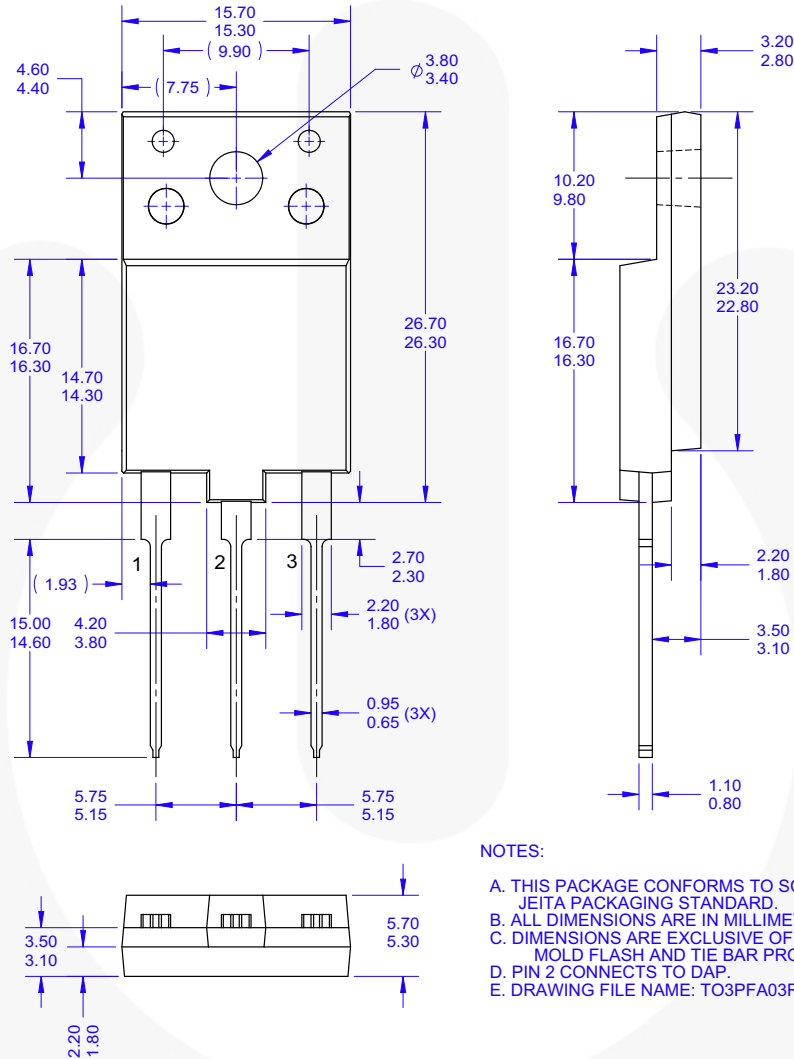


Figure 34. TO-3PF, 3 Leads, Molded, Full Pack

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.





Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:
<http://www.fairchildsemi.com/packaging/>

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area:
http://www.fairchildsemi.com/products/discrete/pdf/to3pf_tr.pdf



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- | | | | |
|--|--|--|---|
| 2Cool™ | F-PFS™ | PowerTrench® | The Power Franchise® |
| AccuPower™ | FRFET® | PowerXS™ | the power franchise |
| AX-CAP™* | Global Power Resource™ | Programmable Active Droop™ | TinyBoost™ |
| BitSiC™ | GreenBridge™ | QFET® | TinyBuck™ |
| Build it Now™ | Green FPS™ | QS™ | TinyCalc™ |
| CorePLUS™ | Green FPS™ e-Series™ | Quiet Series™ | TinyLogic® |
| CorePOWER™ | Gmax™ | RapidConfigure™ | TINYOPTO™ |
| CROSSVOLT™ | GTO™ |  ™ | TinyPower™ |
| CTL™ | IntelliMAX™ | Saving our world, 1mW/W/kW at a time™ | TinyPWM™ |
| Current Transfer Logic™ | ISOPLANAR™ | SignalWise™ | TinyWire™ |
| DEUXPEED® | Making Small Speakers Sound Louder and Better™ | SmartMax™ | TranSiC™ |
| Dual Cool™ | MegaBuck™ | SMART START™ | TriFault Detect™ |
| EcoSPARK® | MICROCOUPLER™ | Solutions for Your Success™ | TRUECURRENT®* |
| EfficientMax™ | MicroFET™ | SPM® | µSerDes™ |
| ESBC™ | MicroPak™ | STEALTH™ |  SerDes™ |
|  Fairchild® | MicroPak2™ | SuperFET® | UHC® |
| Fairchild Semiconductor® | MillerDrive™ | SuperSOT™-3 | Ultra FRFET™ |
| FACT Quiet Series™ | MotionMax™ | SuperSOT™-6 | UniFET™ |
| FACT® | mWSaver™ | SupreMOS® | VCX™ |
| FAST® | OptoHiT™ | SyncFET™ | VisualMax™ |
| FastvCore™ | OPTOLOGIC® | Sync-Lock™ | VoltagePlus™ |
| FETBench™ | OPTOPLANAR® |  SYSTEM GENERAL®* | XS™ |
| FlashWriter®* | | | |
| FPS™ | | | |

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I62